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1. A method for forming a giant magnetoresistive (GMR) sensor element comprising:
    - providing a substrate;
    - forming over the substrate a seed layer, the seed layer being formed of a magnetoresistive (MR) resistivity sensitivity enhancing material selected from the group consisting of nickel-chromium alloys and nickel-iron-chromium alloys;
    - forming over the seed layer a nickel oxide material layer;
    - forming over the nickel oxide material layer a free ferromagnetic layer;
    - forming over the free ferromagnetic layer a non-magnetic conductor spacer layer;
    - forming over the non-magnetic conductor spacer layer a pinned ferromagnetic layer; and
    - forming over the pinned ferromagnetic layer a pinning material layer.

- 2
2. The method of claim 1 wherein the nickel oxide material layer provides an enhanced magnetoresistive (MR) resistivity sensitivity to the giant magnetoresistive (GMR) sensor element.

- 2
3. The method of claim 1 wherein the giant magnetoresistive (GMR) sensor element is selected from the group consisting of simple spin valve magnetoresistive (SVMR) sensor elements, synthetic antiferromagnetically biased giant magnetoresistive (GMR) sensor elements, simple spin filter giant magnetoresistive (GMR) sensor elements and spin filter synthetic antiferromagnetically biased giant magnetoresistive (GMR) sensor elements.

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4. The method of claim 1 wherein the nickel oxide material layer is formed to a thickness of from about 5 to about 15 angstroms as a non-magnetic dielectric nickel oxide material layer.

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5. The method of claim 1 wherein the free ferromagnetic material layer and the pinned ferromagnetic material layer are each formed of a ferromagnetic material selected from the group consisting of nickel, iron and cobalt ferromagnetic materials, alloys thereof, laminates thereof and

laminates of alloys thereof.

6. A giant magnetoresistive (GMR) sensor element comprising:

a substrate;

a seed layer formed over the substrate, the seed layer being formed of a magnetoresistive (MR) resistivity sensitivity enhancing material selected from the group consisting of nickel-chromium alloys and nickel-iron-chromium alloys;

a nickel oxide material layer formed over the seed layer;

a free ferromagnetic layer formed over the nickel oxide material layer;

a non-magnetic conductor spacer layer formed over the free ferromagnetic layer;

a pinned ferromagnetic layer formed over the non-magnetic conductor spacer layer; and

a pinning material layer formed over the pinned ferromagnetic layer.

7. The giant magnetoresistive (GMR) sensor element of claim 6 wherein the giant

magnetoresistive (GMR) sensor element is selected from the group consisting of simple spin valve magnetoresistive (SVMR) sensor elements, synthetic antiferromagnetically biased giant magnetoresistive (GMR) sensor elements, simple spin filter giant magnetoresistive (GMR) sensor elements and spin filter synthetic antiferromagnetically biased giant magnetoresistive (GMR) sensor elements.

8. The giant magnetoresistive (GMR) sensor element of claim 6 wherein the nickel oxide material layer is formed to a thickness of from about 5 to about 15 angstroms as a non-magnetic dielectric nickel oxide material layer.

9. The giant magnetoresistive (GMR) sensor element of claim 6 wherein the free ferromagnetic material layer and the pinned ferromagnetic material layer are each formed of a ferromagnetic

material selected from the group consisting of nickel, iron and cobalt ferromagnetic materials, alloys thereof, laminates thereof and laminates of alloys thereof.

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10. A magnetoresistive (MR) head having incorporated therein a giant magnetoresistive (GMR) sensor element in accord with claim 5

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11. The magnetoresistive (MR) head of claim 10 wherein the magnetoresistive (MR) head is selected from the group consisting of magnetoresistive (MR) read only magnetic heads, merged inductive write magnetoresistive (MR) read magnetic heads and non-merged inductive write magnetoresistive (MR) read magnetic heads.

11  
12. A magnetic data storage enclosure having incorporated therein a magnetoresistive (MR) head in accord with claim 10.

13. A method for forming a spin valve magnetoresistive (SVMR) sensor element comprising:  
providing a substrate;  
forming over the substrate a seed layer, the seed layer being formed of a magnetoresistive (MR) resistivity sensitivity enhancing material selected from the group consisting of nickel-chromium alloys and nickel-iron-chromium alloys;  
forming upon the seed layer a nickel oxide material layer;  
forming upon the nickel oxide material layer a free ferromagnetic layer;  
forming upon the free ferromagnetic layer a non-magnetic conductor spacer layer;  
forming upon the non-magnetic conductor spacer layer a pinned ferromagnetic layer; and  
forming upon the pinned ferromagnetic layer a pinning material layer.

14. The method of claim 13 wherein the nickel oxide material layer provides an enhanced

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magnetoresistive (MR) resistivity sensitivity to the spin valve magnetoresistive (SVMR) sensor element.

15. The method of claim 13 wherein the nickel oxide material layer is formed to a thickness of from about 5 to about 15 angstroms as a non-magnetic dielectric nickel oxide material layer.

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16. The method of claim 13 wherein the free ferromagnetic layer and the pinned ferromagnetic layer are each formed of a ferromagnetic material selected from the group consisting of nickel, iron and cobalt ferromagnetic materials, alloys thereof, laminates thereof and laminates of alloys thereof.

17. A spin valve magnetoresistive (SVMR) sensor element comprising:

a substrate;

a seed layer formed over the substrate, the seed layer being formed of a magnetoresistive (MR) resistivity sensitivity enhancing material selected from the group consisting of nickel-chromium alloys and nickel-iron-chromium alloys;

a nickel oxide material layer formed upon the seed layer;

a free ferromagnetic layer formed upon the nickel oxide material layer;

a non-magnetic conductor spacer layer formed upon the free ferromagnetic layer;

a pinned ferromagnetic layer formed upon the non-magnetic conductor spacer layer; and

a pinning material layer formed upon the pinned ferromagnetic layer.

18. The spin-valve magnetoresistive (SVMR) sensor element of claim 17 wherein the nickel oxide material layer is formed to a thickness of from about 5 to about 15 angstroms as a non-magnetic dielectric nickel oxide material layer.

Figure 1. The 12 test cases used in the study. The test cases are arranged in a 4x3 grid. The first column shows the test cases for the 'low' condition, the second column for the 'medium' condition, and the third column for the 'high' condition. The rows represent different test cases: 'low', 'medium', 'high', and 'very high'.

18  
20. A magnetoresistive (MR) head having incorporated therein a spin-valve magnetoresistive (SVMR) sensor element in accord with claim 17.<sup>15</sup>

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22. A magnetic data storage enclosure having incorporated therein a magnetoresistive (MR) head  
in accord with claim 20.  
18